

S-400-SP5

Micronized EBS Wax

Shamrock's product line of micronized waxes provide rub and abrasion resistance. Included in this line are products that provide gloss, matting, clarity, and controlled slip in a range of particle sizes.



Product Description:

S-400-SP5 is a micronized EBS (ethylene bis stearamide) wax powder showing melting peaks ranging from 142 – 145°C.






Application:

S-400-SP5 is used in both the ink and coating industry. S-400-SP5 is recommended for powder, leather, water-based, solvent-based and UV systems at 1-2% of the total formula weight.

Features and Benefits:

-  Slip (Low COF)
-  Release

Typical Properties:

	Specific Gravity:	0.98 g/cm ³
	Particle Size Mean Value:	10 µm
	99% of Particle Under:	35 µm
	NPIRI Grind:	8.5 Max
	Hegman Grind:	5.5 Min

Regulatory Status

The components of this product are listed on multiple chemical inventories. For specific information on the applicable chemical inventories, please refer to the product SDS. This product is microplastic free as per ECHA Annex XV restrictions.

Safety, Shipping and Handling

For complete shipping, handling, health and safety information please contact your regional Customer Service Representative. Please contact them at your convenience for instructions and Material Safety Data Sheets, the contact information is located below.

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